



akrometrix

Thermal Warpage & Strain Metrology

PS200S Thermal Warpage System

For Fast Thermal Surface Topography

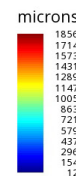
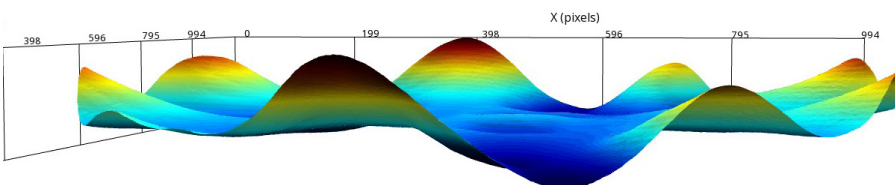
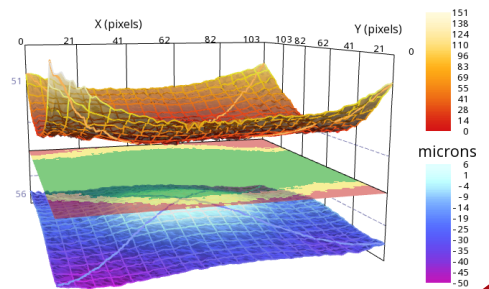
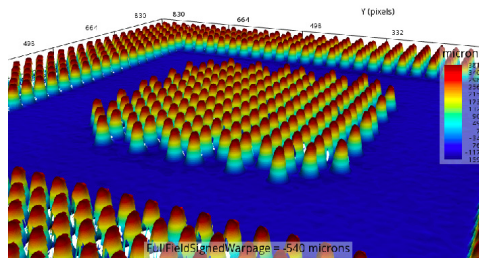
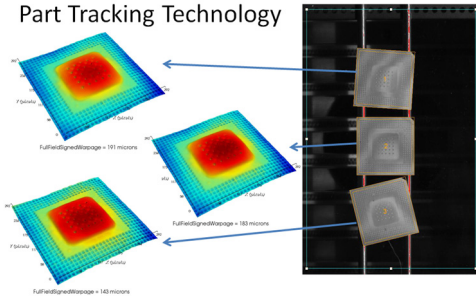
- **Accommodates substrates** up to 200mm x 200mm
- **Field of View Measurement** in 2 seconds
- **With z resolution** down to 0.85 micron
- **Runs on the Akrometrix Studio Software Suite**



ON VIRTUALLY ANY SUBSTRATE

- PCBs
- Panels
- Wafers
- Stacked Die
- Individual Die
- Populated Boards
- Wafers on Film Frame
- Components
- Fan out Wafers

Part Tracking Technology



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PS200S Technical Specifications

	PS200S Base w/ 200 lpi grating	PS200S w/ optional 300 lpi grating
Vision Measurement Technology	Shadow Moiré	
Maximum Field of View (FOV) (mm)	200x200	
Minimum Field of View (FOV) (mm)	90x90	
Maximum Sample Size (mm)	200x200	
Minimum Sample Size (mm)	5x5	
Maximum Measured Surface Coplanarity	1250 microns	250 microns
Resolution, Z-axis (vertical displacement)	2 microns	1 micron
Accuracy, Z-axis (vertical displacement)	2.5 microns / 3%	
Maximum Measurement Points per Acquisition	1,447,680	
Maximum Measurement Density (points per mm ²)	64	140
Minimum Measurement Density (points per mm ²)	24	36
Thermal Processing Technology	Radiant IR	
Maximum Heating Rate, 50°C to 250°C (°C/s)*	1	
Maximum Cooling Rate, 250°C to 125°C (°C/sec)*	1	
Maximum Thermal Profiles	Unlimited	
Maximum Thermal Cycles Time	Unlimited	
Maximum Acquisitions per Cycle	Unlimited	
Automated Data Collection	yes	
Batch Data Analysis	yes	
Software	Akrometrix Studio	
Data Export Formats	.dat, .txt, .png	
Sample Set-up time, typical	2 minutes	
Sample preparation method, typical	none	
Data Acquisition (Measurement) Time, approximate	2 seconds	
Data Analysis Time per Acquisition, approximate	2 seconds	
Approximate Length, Width, Height (mm)	648x1170x1702	
Approximate Weight (kg)	340	
Electrical Requirements	220VAC, 1 phase, 10A	
Air Requirements	N/A	
Other Utilities	exhaust 1800 lpm	

